

Texas Instruments
Analog Reference Design Test Procedure
USB2USB3 Redriver Dongle Test Procedure

Rev. 1

1.0 GENERAL

1.1 PURPOSE

- 1.1.1 This document describes the steps required to perform general USB2USB3 Redriver Dongle functional tests.

1.2 SCOPE

- 1.2.1 Covers complete instructions for testing USB2USB3 Redriver Dongle.

1.3 REFERENCE DOCUMENTATION

- 1.3.1 Schematic USB2_USB3_Redriver_Dongle.dsn
- 1.3.2 Assembly DWG USB2_USB3_Redriver_Dongle.brd

1.4 MATERIALS

- 1.4.1 USB 2.0 or USB 3.0 cable (Type A connector to Type B connector).
- 1.4.2 USB 2.0 or USB 3.0 thumb drive device.

1.5 DEFINITIONS

- 1.5.1 PC – Personal Computer
- 1.5.2 USB – Universal Serial Bus
- 1.5.3 USB thumb drive - Also known as a flash drive or keychain drive -- is a plug-and-play portable storage device that uses flash memory and is lightweight enough to attach to a keychain.

2.0 SAFETY

- 2.1 This test must be performed by qualified personnel trained in electronics theory and understand the risks and hazards of the assembly to be tested.
- 2.2 ESD precautions must be followed while handling electronic assemblies while performing this test.
- 2.4 Precautions should be observed to avoid touching areas of the assembly that may get hot or present a shock hazard during testing.

3.0 QUALITY

- 3.1 Test data or reports shall be made available upon request by Texas Instruments.

4.0 APPAREL

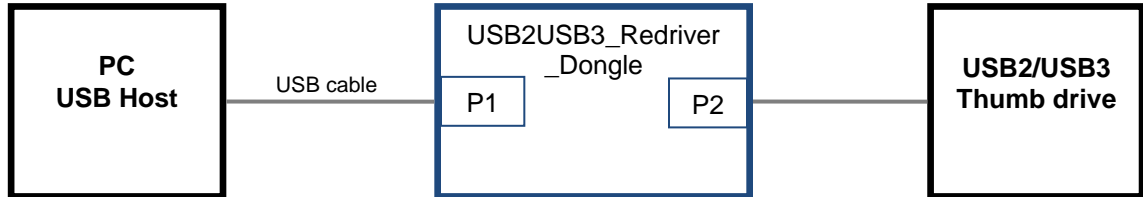
- 4.1 Electrostatic smock
- 4.2 Electrostatic Gloves or finger cots
- 4.3 Ground ESD wrist strap.

5.0 EQUIPMENT

- 5.1 USB2USB3 Redriver Dongle.
- 5.2 PC with USB Host running Windows XP™ or above (32-bits or 64-bits OS).

6.0 EQUIPMENT SETUP

- 6.1 Connect the USB2USB3 Redriver Dongle to a PC which has a USB2/USB3 Host through a Type-A connector to the Type-B connector (P1) of the Reference design.
- 6.2 Attach a USB2/USB3 thumb drive via cable or directly plugged into the Type A receptacle connector (P2) on the USB2USB3 Redriver Dongle.



- 6.3 The USB2USB3 Redriver Dongle Switches doesn't requires any extra configuration.

7.0 PROCEDURE

- 7.1 Ensure the Thumb Drive is listed as an active drive under Computer settings (In Windows, click Start -> Computer).
- 7.2 Make sure that the thumb drive works correctly. Copy some files from the PC to the thumb drive and from the thumb drive to the PC.

8.0 EQUIPMENT SHUTDOWN

- 8.1 Disconnect the USB device (thumb drive) from the USB2USB3 Redriver Dongle and disconnect the USB cable (USB2 OR USB 3) from the USB2USB3 Redriver Dongle Type-B connector (P1).

9.0 MATERIAL DISPOSITION & TRANSFER

9.1 CONFORMING MATERIAL

Units that have passed this test procedure shall be packaged into anti-static ESD approved bags, labeled with two labels according to the table below, and shipped per the P.O.

Label 1 Assembly Number+Dash Number if Applicable	Label 2 IC Number
USB2USB3 Redriver Dongle	TUSB211RWBR, TUSB501DRF

9.2 NON-CONFORMING MATERIAL

If yield loss is 2% or less, scrap non-conforming units and adjust P.O. to reflect total amount shipped. If yield loss approaches or exceeds 5%, contact EVM coordinator for assistance.

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